

ABSTRACT

A method of connecting an electronic part,
containing: forming an electroless nickel plating coat
5 containing phosphorous on a substrate metal layer which
constitutes a connecting terminal of an electronic part;
and carrying out connecting to the nickel plating coat
through a lead-free solder, wherein a half-width of X-ray
diffraction of a (111) plane of Ni crystal in the nickel
10 plating coat is 5 degrees or less.